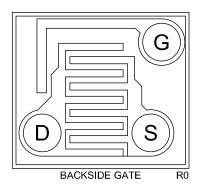


# CP264V-2N5457

# **N-Channel JFET Die**

The CP264V-2N5457 is a silicon N-Channel JFET designed for switching and amplifier applications.



### **MECHANICAL SPECIFICATIONS:**

Die Size	17.1 x 15.1 MILS
Die Thickness	7.9 MILS
Drain Bonding Pad Size	3.7 MILS DIAMETER
Source Bonding Pad Size	3.7 MILS DIAMETER
Gate Bonding Pad Size	3.7 MILS DIAMETER
Top Side Metalization	Al-Si – 17,000Å
Back Side Metalization	Au – 12,000Å
Scribe Alley Width	1.96 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	59,783

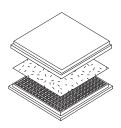
MAXIMUM RATINGS: (TA=25°C)	SYMBOL		UNITS
Drain-Source Voltage	$V_{DS}$	25	V
Drain-Gate Voltage	$V_{DG}$	25	V
Gate-Source Voltage	$V_{GS}$	25	V
Continuous Gate Current	$I_{G}$	10	mA
Operating and Storage Junction Temperature	Tu Tota	-65 to +150	°C

**ELECTRICAL CHARACTERISTICS**: (T<sub>A</sub>=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
IGSS	V <sub>GS</sub> =15V		1.0	nA
IDSS	V <sub>DS</sub> =15V	1.0	5.0	mA
$BV_GSS$	I <sub>G</sub> =10µA	25		V
V <sub>GS(OFF)</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =10nA	0.5	6.0	V
C <sub>rss</sub>	$V_{DS}$ =15V, $V_{GS}$ =0, f=1.0MHz		3.0	pF
C <sub>iss</sub>	$V_{DS}$ =15V, $V_{GS}$ =0, f=1.0MHz		7.0	pF
9fs	$V_{DS}$ =15V, $V_{GS}$ =0, f=1.0kHz	1.0K	5.0K	μS
gos	V <sub>DS</sub> =15V, V <sub>GS</sub> =0, f=1.0kHz		50	μS

# BARE DIE PACKING OPTIONS



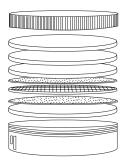


# BARE DIE IN TRAY (WAFFLE) PACK

CT: Singulated die in tray (waffle) pack.

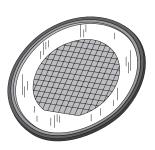
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-PART NUMBER-CM)



# **UNSAWN WAFER**

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



#### SAWN WAFER ON PLASTIC RING

**WR**: Full wafer, sawn and mounted on plastic ring,

100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

R2 (3-April 2017)

#### **OUTSTANDING SUPPORT AND SUPERIOR SERVICES**



#### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

#### **DESIGNER SUPPORT/SERVICES**

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- · Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

#### REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

#### **CONTACT US**

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